

L-Band, GaN/SiC, RF Power Transistor

1.2 - 1.4 GHz | 300 W typ | 65% Efficiency typ | 16dB Gain typ | 50 V | 300µs Pulse Length, 10% Duty Cycle

IGN1214M250 and IGN1214M250S are high power GaN-on-SiC RF power transistors that have been designed to suit the unique needs of modern radar systems. They supply a minimum of 250 W of peak output power, with typically >16 dB of gain and 65% efficiency. They operate from a 50 V supply voltage. For optimal thermal efficiency, the transistors are housed in a metal-based package with an epoxy-sealed ceramic lid.



FEATURES

- GaN on SiC HEMT Technology
- Output Power >250 W
- Pre-matched Input and Output Impedance
- High Efficiency - typically 65%
- 100% RF Tested Under 300µs, 10% duty cycle pulse conditions
- RoHS and REACH Compliant

APPLICATIONS

- L-band Radar Systems

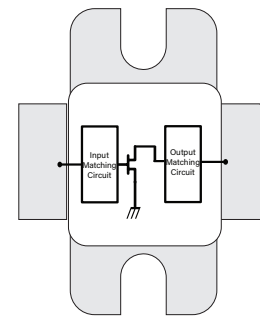


Table 1. Absolute Maximum Ratings (Not Simultaneous)

Parameter	Symbol	Value	Units	Test Conditions
DC Drain-Source Voltage	V_{DS}	120	V	25 °C
DC Gate-Source Voltage	V_{GS}	-8 to +1	V	25 °C
DC Drain Current	I_D	24	A	25 °C
DC Gate Current	I_G	24	mA	25 °C
RF Input Power	$P_{RF,IN}$	14	W	25 °C
Operating Channel Temperature	T_{CH}	-55 to +225	°C	
Storage Temperature	T_{STG}	-55 to +150	°C	
Soldering Temperature	T_{SOLDER}	260 for 60s	°C	

Note: Operation outside the limits given in this table may cause permanent damage to the transistor

Table 2. DC Electrical Characteristics (Case temperature = 25 °C unless otherwise stated)

Parameter	Symbol	Min	Typ	Max	Units	Test Conditions
Gate Pinch-Off Voltage	V_P	-5.0			V	$V_{DS} = 50V, I_{DS} = 1mA$
Quiescent Gate Voltage	V_Q		-2.8		V	$V_{DS} = 50V, I_{DS} = 100mA$

Table 3. RF Electrical Characteristics (Case temperature = 30 °C unless otherwise stated)

Parameter	Symbol	Min	Typ	Max	Units	Test Conditions
RF Output Power	$P_{OUT,RF}$	250	320	350	W	$P_{IN} = 8W$ $f = 1.2, 1.3, 1.4 \text{ GHz}$ 300 μ s pulse length 10% duty cycle pulse conditions $V_{DS} = 50V, I_{DS} = 100mA$
Gain	G	15.0	16.0	16.5	dB	
Drain Efficiency	η	50	60	75	%	
Pulse Droop	D	-0.5	-0.25	+0.2	dB	
Input Return Loss	IRL	7	12	20	dB	
Load Mismatch Stability	VSWR-S	2:1				
VSWR Withstand	VSWR-LMT	3:1				

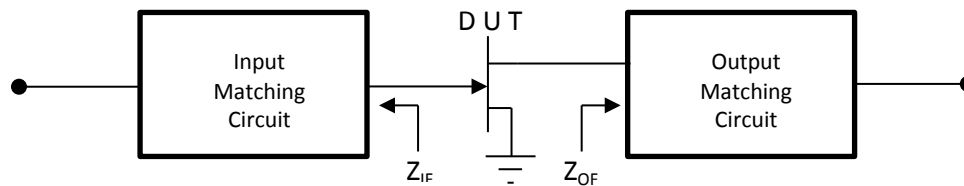
Note: Consult Integra Technologies Application Note 001 for information on how RF output power and pulse droop are measured.

Table 4. Thermal Resistance (Case temperature = 85 °C unless otherwise stated)

Parameter	Symbol	Min	Typ	Max	Units	Test Conditions
Peak Thermal Resistance, Channel to Case	R_{TH}		0.65		°C/W	$P_{DISS} = 213W$ 300 μ s pulse length 10% duty cycle $V_{DS} = 50V$

Table 5. Test Fixture Source & Load Impedances (Case temperature = 25 °C unless otherwise stated)

Frequency (GHz)	Z_{IF}	Z_{OF}	Units	Test Conditions
1.2	$3.0 - j1.0$	$4.15 - j2.9$	Ω	$P_{OUT} = 250W$ 300 μ s pulse length 10% duty cycle $V_{DS} = 50V, I_{DS} = 100mA$
1.3	$3.15 + j0.25$	$4.4 - j2.9$	Ω	
1.4	$3.35 + j1.6$	$4.05 - j2.8$	Ω	



TYPICAL PERFORMANCE

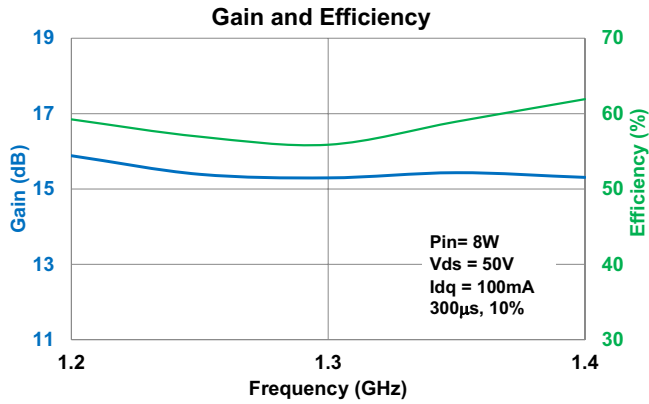


Figure 1

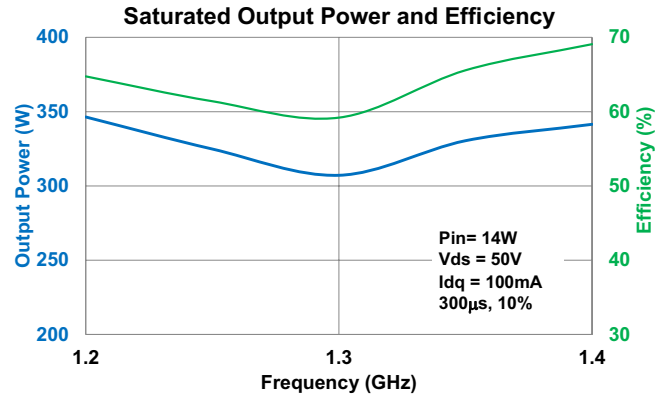


Figure 2

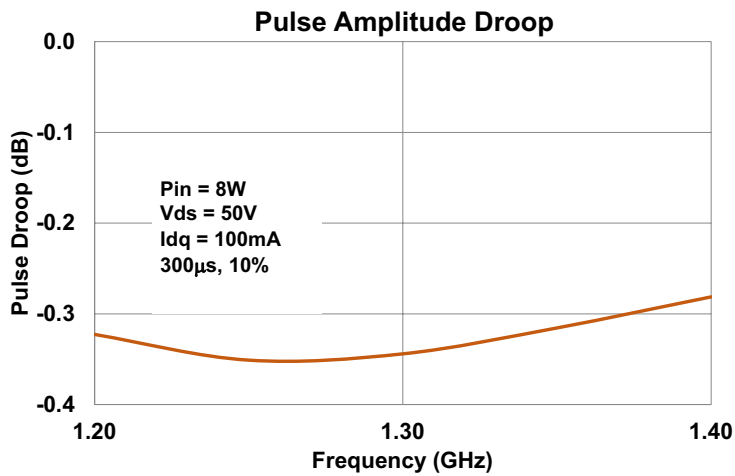


Figure 3

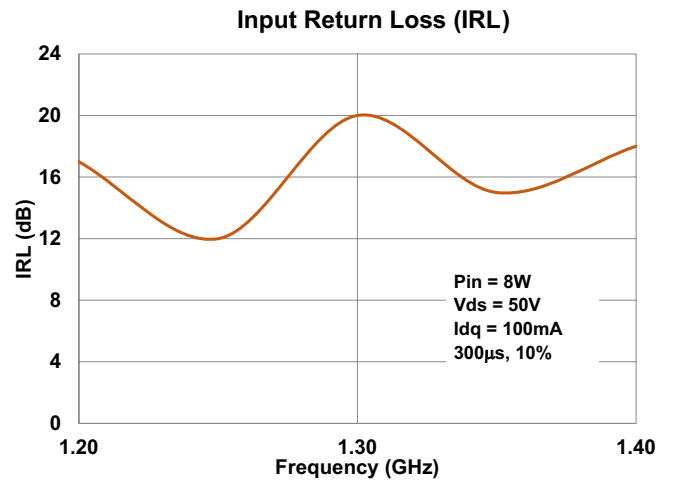
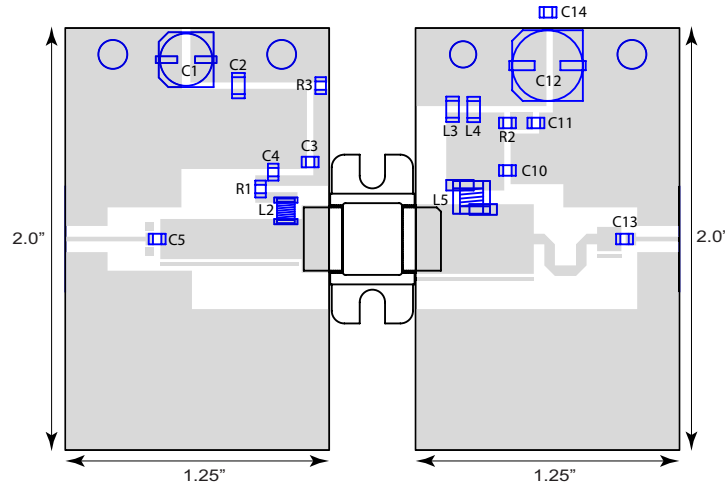


Figure 4

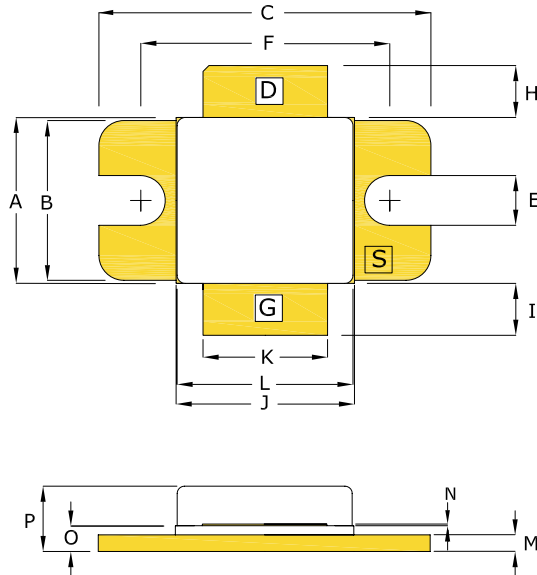
TEST FIXTURE



Bill of Materials for IGN1214M250 Test Fixture

Designator	Description	Part Number
C1	CAP 47 μ F, 25V, Electrolytic	PCV1E470MCL2GS
C2	CAP 1 μ F, 1206, 50V, X7R	12061C105K4T2A
C3, C11	CAP 0.1 μ F, 0805, 50V, X7R	08051C104K4T2A
C4, C5, C10, C13	CAP 18pF, 0805	600F180JT250XT
C12	CAP 68 μ F, 63V, Electrolytic	EEE-FK1J680P
C14	CAP 4700 μ F, 63V, Electrolytic	UVR1J472MRD6
L2	IND 27.3nH, 0908	0908SQ-27N
L3, L4	IND FB 33 OHM, 1206, 6A	BLM31PG330SN1L
L5	IND 18.5nH	A05TJL
R1, R2	RES 10 OHM, 0805	ERJ-6ENF10R0V
R3	RES 390 OHM, 0805	ERJ-6GEYJ391V
PC Board Type	ROGERS RT6010.2, 25mil, 1/1oz. Copper	

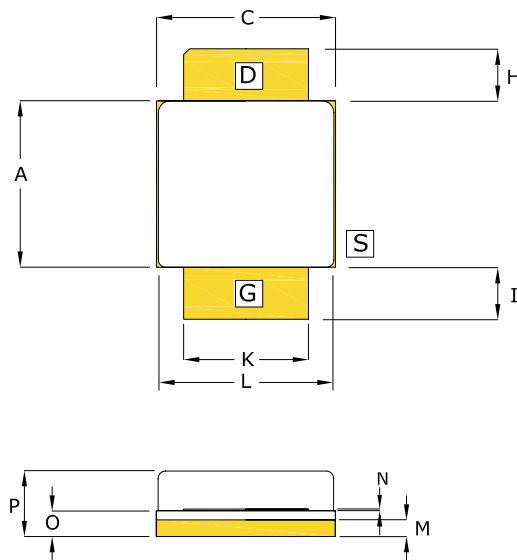
PACKAGE PL44C1



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.395	0.405	10.03	10.29
B	0.380	0.390	9.65	9.91
C	0.795	0.805	20.19	20.45
E	0.115	0.125	2.92	3.18
F	0.595	0.605	15.11	15.37
H	0.110	0.140	2.79	3.56
I	0.110	0.140	2.79	3.56
J	0.425	0.435	10.80	11.05
K	0.295	0.305	7.49	7.75
L	0.420	0.428	10.67	10.87
M	0.035	0.045	0.89	1.14
N	0.004	0.007	0.10	0.18
O	0.053	0.067	1.35	1.70
P	0.143	0.179	3.63	4.55

PIN SCHEDULE	
D	DRAIN
S	SOURCE
G	GATE

**BOLT-DOWN FLANGE OPTION
IGN1214M250**



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.393	0.408	9.97	10.35
B	--	--	--	--
C	0.423	0.438	10.73	11.11
E	--	--	--	--
F	--	--	--	--
H	0.110	0.140	2.79	3.56
I	0.110	0.140	2.79	3.56
J	--	--	--	--
K	0.295	0.305	7.49	7.75
L	0.420	0.428	10.67	10.87
M	0.035	0.045	0.89	1.14
N	0.004	0.007	0.10	0.18
O	0.053	0.067	1.35	1.70
P	0.143	0.179	3.63	4.55

PIN SCHEDULE	
D	DRAIN
S	SOURCE
G	GATE

**EARLESS FLANGE OPTION
IGN1214M250S**

ESD & MSL Rating

Parameter	Rating	Standard
ESD Human Body Model (HBM)	TBD	ESDA/JEDEC JS-001-2012
ESD Charged Device Model (CDM)	TBD	JEDEC JESD22-C101F
Moisture Sensitivity Level (MSL)	Unlimited Shelf Life	IPC/JEDEC J-STD-020

RoHS Compliance

Integra Technologies, Inc declares that its GaN and LDMOS Transistor Products comply with EU Directive 2011/65/EU on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS2), as adopted by EU member states on January 2, 2013 and amended on March 31, 2015 by EU Directive 2015/863/EU.

REACH Compliance

Integra Technologies supports EU Regulation number 1907/2006 concerning the Registration, Evaluation, Authorization, and Restriction of Chemicals (REACH) as these apply to Integra semiconductor products, development tools, and shipping packaging.

In support of the REACH regulation, Integra will:

- Inform customers and recipients of Integra product if they contain any substances that are of very high concern (SVHC) per the European Chemical Agency (ECHA) website.
- Notify ECHA if any Integra product that contains any SVHCs which exceed guidelines for REACH chemicals by weight per part number and for total content weight per year for all products produced in or imported to the European market.
- Cease shipments of product containing REACH Annex XIV substances until authorization has been obtained.
- Cease shipment of product containing REACH Annex XVII chemicals when restrictions apply.

Integra has evaluated its materials, BOMs, and product specifications and product and has determined that this transistor conforms to all REACH and SVHC regulations and guidelines. Integra has implemented actions and control programs that will assure continued compliance.

Disclaimer

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DEFINITIONS:

DATA SHEET STATUS

Advanced Specification - This data sheet contains Advanced specifications.

Preliminary Specification - This data sheet contains specifications based on preliminary measurements and data.

Final Specification - This data sheet contains final product specifications.

MAXIMUM RATINGS Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.